

IEC TC106 MT1- 62209
Ottawa - Canada
September 30 – October 2, 2013

REPRESENTATION

Over 40 participants represented four major groups:

1. Manufacturers:

Samsung
Nokia
Motorola
Motorola Solutions
Apple
LG

2. Independent Labs:

APREL (CA)
Field Imaging (Fr)
PC Test (US)
Satimo (US)
IT'IS (Sw)
NICT (Jp)
ETRI (Ch)
NTT Docomo (Jp)
IMST (De)

3. Carriers:

Vodafone

4. Regulators:

Industry Canada
Japan

Canadian delegation:

Hughes Nappert (IC)
Stephane Proulx (IC)
Josette Gallant (IC)
Francois Menard (IC)
Dupuis Marc(IC)
Maryna Nesterova (APREL)

MAIN SUBJECTS DISCUSSED

New IEC 62209-1 CDV is to be circulated in February 2014.

Quick Start Guide – schematic presentation of SAR measurement procedure requirements.

LTE SAR measurements:

1. Dr. Teuro Onishi (Japan) presented the report on ad-hoc team activities.
2. Benoit Derat (France), the relationship between maximum SAR and Conducted Power.

Hand effect on Head SAR:

1. Andreas Christ (Brazil), presented new data on hand effect One observation to date is that SAR volumes are more spread out than expected. A Clear correlation between psSAR and antenna size is demonstrated.
2. Maryna Nesterova (Canada), presented work requirements for the frequency bands below 900MHz and above 1900MHz to try and validate the uncertainty budget.

Tissue liquid study (62209-2):

1. Goga Bit-Babik (USA) presented tissue liquid study report.

Proximity Sensors:

1. Mauro Francavilla (Italy), presented the update of activities of the proximity sensor ad-hoc groups and drafts of the Clause text.

APREL INVOLVEMENT

Participation in the Hand Effect Annex ad-hoc group.

Participation in the LTE SAR measurements ad-hoc group.

SUMMARY

1. All NC comments should be revised and addressed in the new draft.
2. The LTE device SAR measurement procedures should be based on the optimized FCC KDB, and requirements of Japanese and Korean regulators.
3. Further studies on Hand SAR effect are required.
4. No significant progress on Part 2 (Body).
5. LTE and Proximity Sensors sections should be ready to be incorporated into the upcoming IEC 62209 version.